



**FEEDING EQUIPMENT
DIE EJECT UNIT WITH SINGLE WAFER LOADER**

SKU: S3-0097.01

79.000,00 € excl. VAT



Categories: Feeding equipment, Modules

BESCHREIBUNG

The wafer system consisting of Die Eject Unit and Single Wafer Loader is used to load wafers and to release components from the wafer foil to make them available to the machine for further processing. The components fixed on the wafer foil are released with a Needle Vacuum System and thus separated.

The Single Wafer Loader is used to feed a wafer to be processed and to remove the processed wafer. Only one Wafer can be fed or removed at a time.

The wafers are fed in without opening the doors of the machine.

The Single Wafer Loader is equipped with a laser safety window, which allows the wafer system to be used in machines with laser applications.

MORE INFORMATIONS

Dimensions in mm (W x D x H)	428,5 x 756,5 x 253
Max. wafer size in inch / mm	8 / 200
Voltage in V	24
Max. current in A	5
Communication interface	Ethernet, UNICAN

Häcker Automation GmH
Inselsbergstraße 17
99880 Waltershausen / OT
Schwarzhausen

mikromontage.shop

Contact us:

Consulting: +49 (0)36259 300 99

Support: +49 (0)36259 300 711

E-Mail: contact@haecker-automation.com

